

ABSTRACT**METHOD FOR MOLECULAR ADHESION BONDING WITH
COMPENSATION FOR RADIAL MISALIGNMENT**

5 A method for bonding a first wafer (100) on a second wafer
(200) by molecular adhesion, the said wafers having an initial radial
misalignment between them. The said method comprises at least one step
of bringing the two wafers (100, 200) into contact so as to initiate the
propagation of a bonding wave between the two wafers. According to the
10 invention, a predefined bonding curvature (K_B) is imposed on at least one
of the two wafers during the contacting step as a function of the initial
radial misalignment.

Fig. 5D and 5E